

Comparison of Contamination Effects in Silicon Oxide with that in Hafnium Oxide and Zirconium Oxide Gate Dielectrics

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The objective of this study was to study the effect of airborne molecular contamination in silicon dioxide and compare it with that of zirconium and hafnium dioxides considered as future gate dielectrics. The adsorption-desorption properties of moisture and organic contaminants on 50 Å thin films are grown or deposited by ALCVD are presented. Even a highly controlled ambient in modern processing environments contains parts-per-billion (ppb) levels of molecular contaminants, which can affect dielectric performance. Hence, most of the experiments were performed at ppb levels of contamination. Also presented is a direct comparison of the extent and energetics of contamination on HfO₂ with that of ZrO₂ and SiO₂ surfaces. Such a study can offer valuable insights into the relative levels of contamination of various gate dielectrics. It should also facilitate selection of the most appropriate dielectric film and design of process/equipment so that it can be more readily integrated into silicon technology.

Results and Discussion

Figure 1 shows the experimental set up for developed for this study. Figure 2 compares total amount of moisture adsorbed on HfO₂, ZrO₂ and SiO₂ surfaces at different temperatures for a 56 ppb challenge. For the same challenge concentration, the amount of moisture adsorbed was higher on HfO₂ and ZrO₂ than on SiO₂ at any given temperature. The greater rate of change in adsorption amount with respect to temperature for HfO₂ and ZrO₂ suggests that moisture contamination in HfO₂ and ZrO₂ is more problematic than that in SiO₂. Similar results for organic contamination shows that ZrO₂ had the highest adsorption loading, HfO₂ had the second highest loading, and SiO₂ was the lowest. Atmospheric molecular contamination can affect the quality of all three gate dielectric film studied. HfO₂ and ZrO₂ have similar moisture adsorption loading, but significantly higher than that of SiO₂. However, almost all the adsorbed moisture can be

removed from SiO₂ and HfO₂ after a 300 °C bake under nitrogen purge, whereas ZrO₂ surfaces retain 20–30 % of the adsorbed moisture. Experiments with isopropanol show that the adsorption loading on the three surfaces has the following order: ZrO₂ > HfO₂ > SiO₂. A multi-layer model (Figure 3) for adsorption of water and IPA is developed to understand the mechanism of interactions of contaminants with the three surfaces. Results from the application of this multi-layer model to the experimental data indicate that ZrO₂ forms the strongest surface–hydroxyl (X–OH) bond.

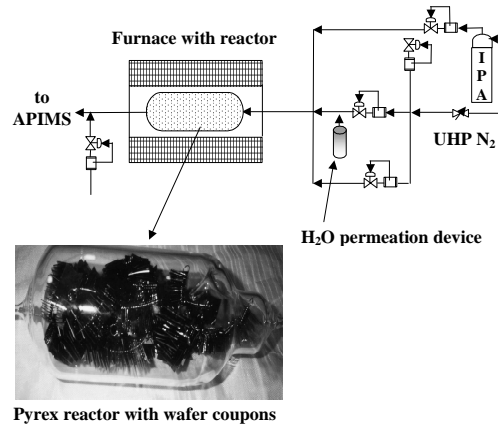


Figure 1. Schematic of the experimental set up

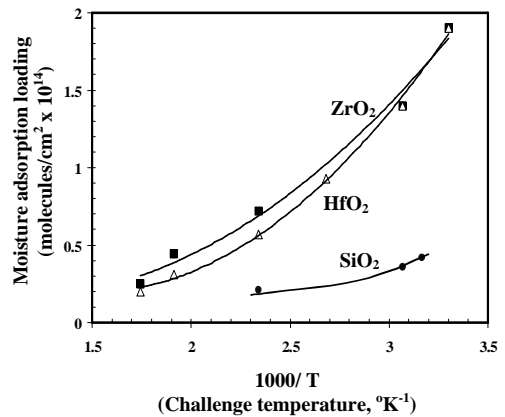


Figure 2. Comparison of contamination in three dielectric oxides

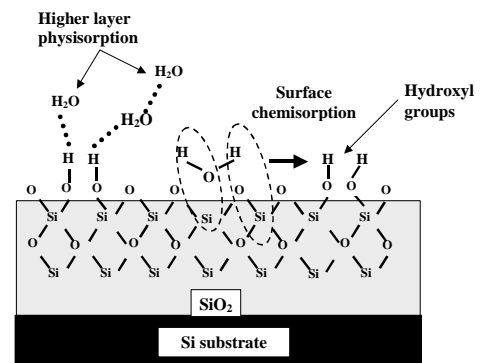


Figure 3. Chemical model for contamination adsorption and desorption

